

54F/74F2620 • 54F/74F2623 Inverting Octal Bus Transceiver with 25 Ω Series Resistors in the Outputs

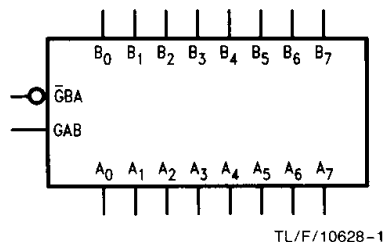
General Description

These devices are octal bus transceivers designed for asynchronous two-way data flow between the A and B busses. These devices are functionally equivalent to the 'F620 and 'F623. The 25 Ω series resistors in the outputs reduce ringing and eliminate the need for external resistors. Both busses are capable of sinking 12 mA, sourcing 15 mA, and have TRI-STATE outputs. Dual enable pins (GAB, $\overline{\text{GAB}}$) allow data transmission from the A bus to the B bus or from the B bus to the A bus. The 'F2620 is an inverting option of the 'F2623.

Features

- 25 Ω series resistors in the outputs eliminate the need for external resistors.
- Designed for asynchronous two-way data flow between busses
- Outputs sink 12 mA and source 15 mA
- Dual enable inputs control direction of data flow
- Guaranteed 4000V minimum ESD protection
- 'F2620 is an inverting option of the 'F2623

Logic Symbol

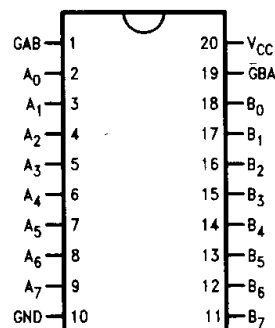


Unit Loading/Fan Out

Pin Names	Description	54F/74F	
		U.L. HIGH/LOW	Input I_{IH}/I_{IL} Output I_{OH}/I_{OL}
$\overline{\text{GAB}}$, GAB	Enable Inputs	1.0/1.0	20 μA / -0.6 mA
A ₀ -A ₇	A Inputs or TRI-STATE Outputs	3.5/0.667	70 μA / -0.4 mA -15 mA/12 mA
B ₀ -B ₇	B Inputs or TRI-STATE Outputs	3.5/0.667	70 μA / -0.4 mA -15 mA/12 mA

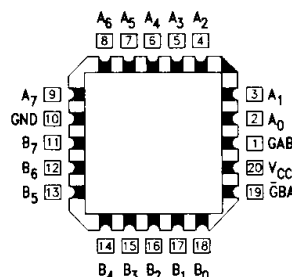
Connection Diagrams

Pin Assignment for
DIP, SOIC and Flatpak



TL/F/10628-2

Pin Assignment
for LCC



TL/F/10628-3

Functional Description

The enable inputs GAB and $\overline{\text{GBA}}$ control whether data is transmitted from the A bus to the B bus or from the B bus to the A bus. If both $\overline{\text{GBA}}$ and GAB are disabled ($\overline{\text{GBA}}$ HIGH and GAB low), the outputs are in the high impedance state and data is stored at the A and B busses. When $\overline{\text{GBA}}$ is active (LOW), B data is sent to the A bus. When GAB is active (HIGH), data from the A bus is sent to the B bus. If both enable inputs are active ($\overline{\text{GBA}}$ LOW and GAB HIGH) B data is sent to the A bus while A data is sent to the B bus.

Function Table

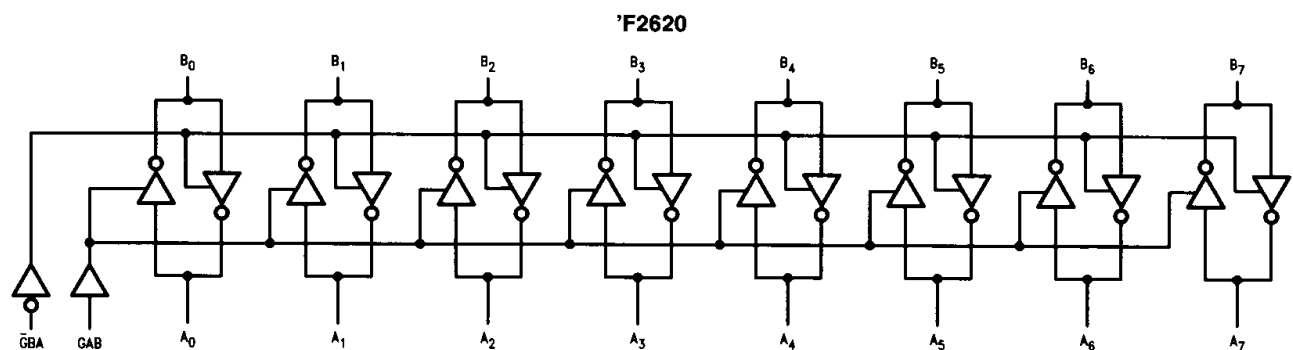
Enable Inputs		Operation	
$\overline{\text{GBA}}$	GAB	'F2620	'F2623
L	L	$\overline{\text{B}}$ Data to A Bus	B Data to A Bus
H	H	$\overline{\text{A}}$ Data to B Bus	A Data to B Bus
H	L	Z	Z
L	H	$\overline{\text{B}}$ Data to A Bus, $\overline{\text{A}}$ Data to B Bus	B Data to A Bus, A Data to B Bus

H = HIGH Voltage Level

L = LOW Voltage Level

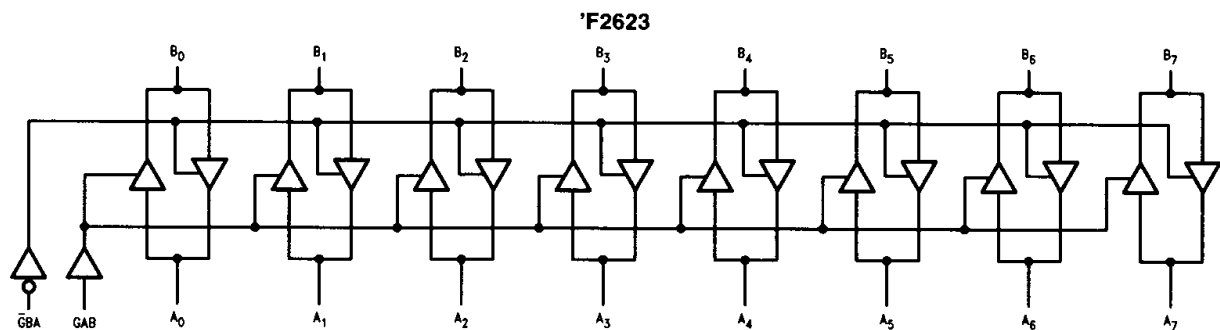
Z = High Impedance

Logic Diagram



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Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.



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Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Storage Temperature	−65°C to +150°C
Ambient Temperature under Bias	−55°C to +125°C
Junction Temperature under Bias	−55°C to +175°C
V _{CC} Pin Potential to Ground Pin	−0.5V to +7.0V
Input Voltage (Note 2)	−0.5V to +7.0V
Input Current (Note 2)	−30 mA to +5.0 mA

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

Voltage Applied to Output in HIGH State (with V _{CC} = 0V)	−0.5V to V _{CC}
Standard Output TRI-STATE Output	−0.5V to +5.5V
Current Applied to Output in LOW State (Max)	twice the rated I _{OL} (mA)
ESD Last Passing Voltage (Min)	4000V

Recommended Operating Conditions

Free Air Ambient Temperature	−55°C to +125°C
Military Commercial	0°C to +70°C
Supply Voltage	+4.5V to +5.5V
Military Commercial	+4.5V to +5.5V

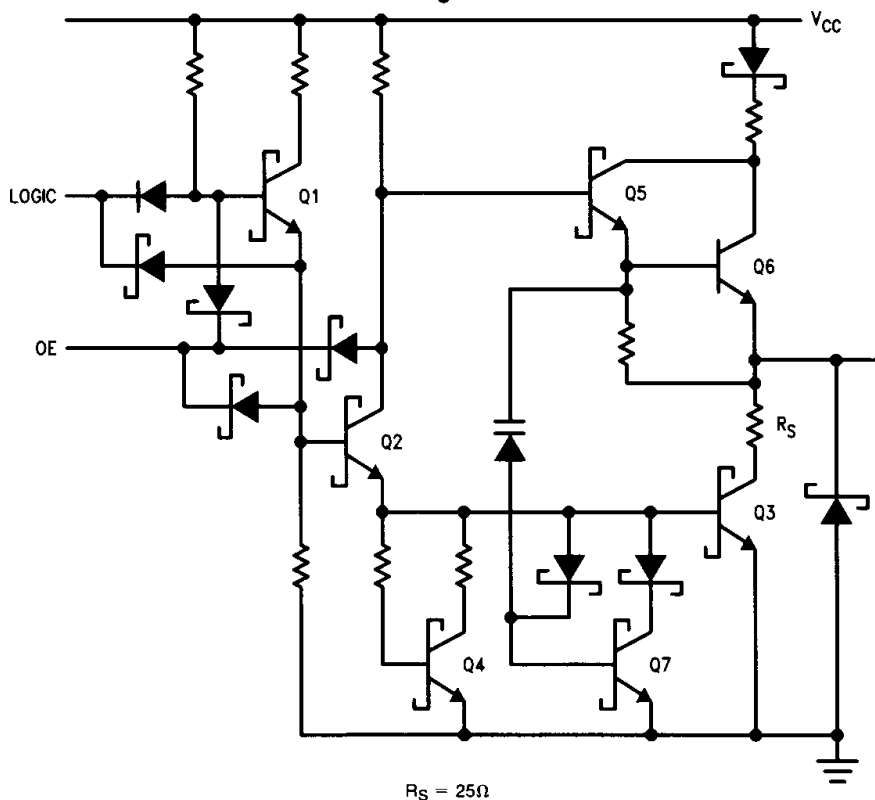
DC Electrical Characteristics

Symbol	Parameter	54F/74F			Units	V _{CC}	Conditions
		Min	Typ	Max			
V _{IH}	Input HIGH Voltage	2.0			V		Recognized as a HIGH Signal
V _{IL}	Input LOW Voltage			0.8	V		Recognized as a LOW Signal
V _{CD}	Input Clamp Diode Voltage			−1.2	V	Min	I _{IN} = −18 mA (Non I/O Pins)
V _{OH}	Output HIGH Voltage	54F 10% V _{CC} 74F 10% V _{CC}	2.0 2.0		V	Min	I _{OH} = −12 mA (A _n , B _n) I _{OH} = −15 mA (A _n , B _n)
V _{OL}	Output LOW Voltage			0.5 0.75	V	Min	I _{OL} = 1.0 mA (A _n , B _n) I _{OL} = 12 mA (A _n , B _n)
I _{IH}	Input HIGH Current	54F 74F		20.0 5.0	μA	Max	V _{IN} = 2.7V (Non I/O Pins)
I _{BVI}	Input HIGH Current Breakdown Test	54F 74F		100 7.0	μA	Max	V _{IN} = 7.0V (Non I/O Pins)
I _{BVIT}	Input HIGH Current Breakdown Test (I/O)	54F 74F		1.0 0.5	mA	Max	V _{IN} = 5.5V (A _n , B _n)
I _{CEX}	Output HIGH Leakage Current	54F 74F		250 50	μA	Max	V _{OUT} = V _{CC}
V _{ID}	Input Leakage Test	74F	4.75		V	0.0	I _{ID} = 1.9 μA All Other Pins Grounded
I _{OD}	Output Leakage Circuit Current	74F		3.75	μA	0.0	V _{IOD} = 150 mV All Other Pins Grounded
I _{IL}	Input LOW Current			−0.6	mA	Max	V _{IN} = 0.5V (Non I/O Pins)
I _{IH} + I _{OZH}	Output Leakage Current			70	μA	Max	V _{OUT} = 2.7V (A _n , B _n)
I _{IL} + I _{OZL}	Output Leakage Current			−650	μA	Max	V _{OUT} = 0.5V (A _n , B _n)
I _{OS}	Output Short-Circuit Current		−100	−225	mA	Max	V _{OUT} = 0V
I _{ZZ}	Bus Drainage Test			500	μA	0.0V	V _{OUT} = 5.25V
I _{CCH}	Power Supply Current ('F2620)			82	mA	Max	V _O = HIGH, V _{IN} = 0.2V
I _{CCL}	Power Supply Current ('F2620)			82	mA	Max	V _O = LOW
I _{CCZ}	Power Supply Current ('F2620)			95	mA	Max	V _O = HIGH Z
I _{CCH}	Power Supply Current ('F2623)			82	mA	Max	V _O = HIGH
I _{CCL}	Power Supply Current ('F2623)			82	mA	Max	V _O = LOW, V _{IN} = 0.2V
I _{CCZ}	Power Supply Current ('F2623)			95	mA	Max	V _O = HIGH Z

AC Electrical Characteristics

Symbol	Parameter	74F			54F		74F		Units
		$T_A = +25^{\circ}\text{C}$ $V_{CC} = +5.0\text{V}$ $C_L = 50\text{ pF}$			$T_A, V_{CC} = \text{Mil}$ $C_L = 50\text{ pF}$		$T_A, V_{CC} = \text{Com}$ $C_L = 50\text{ pF}$		
		Min	Typ	Max	Min	Max	Min	Max	
t_{PLH} t_{PHL}	Propagation Delay A Input to B Output ('F2620)	2.5 3.0		7.5 8.0			2.0 3.0	8.0 8.0	ns
t_{PLH} t_{PHL}	Propagation Delay B Input to A Output ('F2620)	2.5 3.0		7.5 8.0			2.0 3.0	8.0 8.0	ns
t_{PLH} t_{PHL}	Propagation Delay A Input to B Output ('F2623)	1.5 2.5		6.5 7.5			1.5 2.5	7.5 8.0	ns
t_{PLH} t_{PHL}	Propagation Delay B Input to A Output ('F2623)	1.5 2.5		6.5 7.5			1.5 2.5	7.5 8.0	ns
t_{pZH} t_{pZL}	Enable Time $\overline{G}BA$ Input to A Output	2.0 2.5		7.0 8.0			2.0 2.0	8.0 8.5	ns
t_{pHZ} t_{pLZ}	Disable Time $\overline{G}BA$ Input to A Output	1.5 1.0		6.5 5.5			1.5 1.0	7.5 5.5	
t_{pZH} t_{pZL}	Enable Time GAB Input to B Output ('F2620)	2.0 3.0		7.5 8.0			2.0 2.0	8.5 8.5	ns
t_{pHZ} t_{pLZ}	Disable Time GAB Input to B Output ('F2620)	2.5 2.0		8.0 7.5			2.0 2.0	9.0 8.0	
t_{pZH} t_{pZL}	Enable Time GAB Input to B Output ('F2623)	2.0 2.5		7.5 8.0			2.0 2.0	8.5 8.5	ns
t_{pHZ} t_{pLZ}	Disable Time GAB Input to B Output ('F2623)	2.0 2.0		8.0 8.0			2.0 2.0	9.0 8.0	

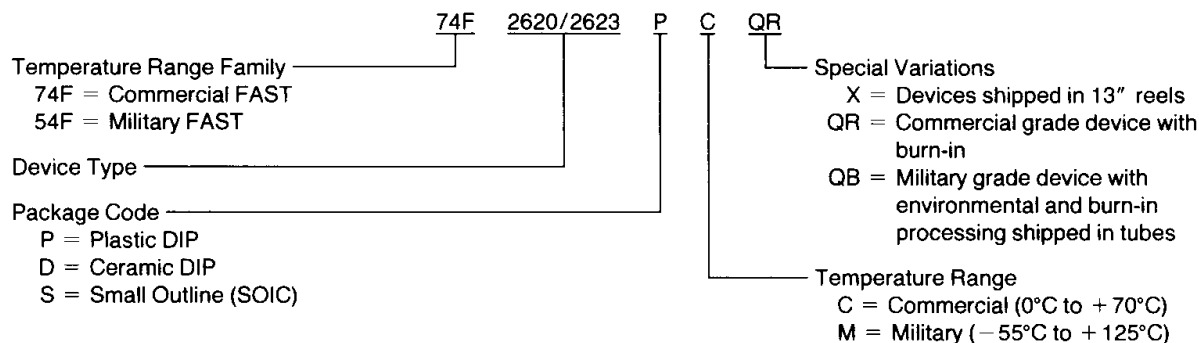
Basic FAST Circuit Showing Series Resistor Placement



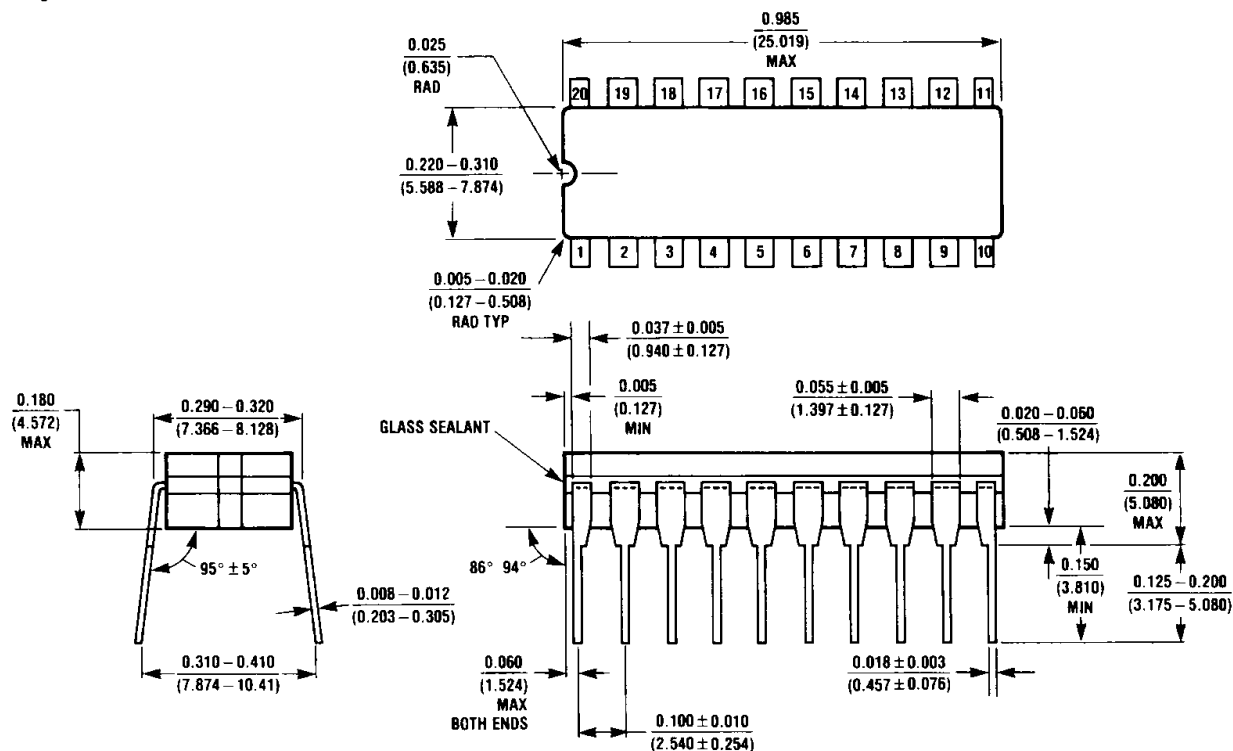
TL/F/10628-6

Ordering Information

The device number is used to form part of a simplified purchasing code where a package type and temperature range are defined as follows:



Physical Dimensions inches (millimeters)

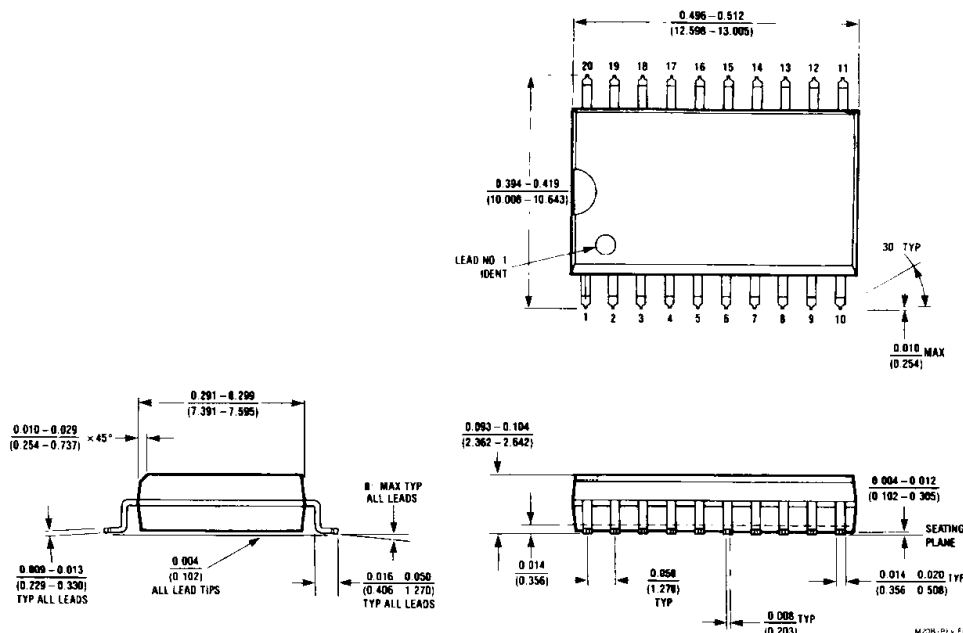


20-Lead Ceramic Dual-In-Line Package (D)
NS Package Number J20A

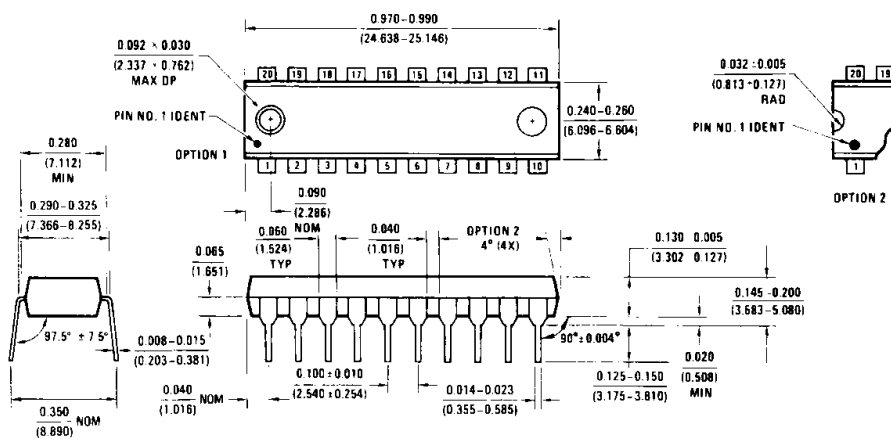
J20A (REV M)

Physical Dimensions inches (millimeters) (Continued)

Lit. # 114658



20-Lead Small Outline Integrated Circuit (S)
NS Package Number M20B



20-Lead Plastic Dual-In-Line Package (P)
NS Package Number N20B

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